



PATENT APPLICATION
Docket No.: 9903-070
Client No.: S02US037

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Hee-Jin Park, et al. Conf. No.: 1321
Serial No. 10/719,670 Examiner: Tho V. Duong
Filed: November 20, 2003 Group Art Unit: 3743
For: STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO ELECTION REQUIREMENT

Responsive to the Restriction Requirement, dated August 12, 2004, Applicant hereby elects Species represented by FIG 3., with traverse. Claims 1-2, 7-14, and 17-20 read on this species.

Customer No. 20575

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, PC

Hosoon Lee
Limited Recognition Under 37 CFR § 10.9(b)

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450
Date: September 1, 2004

Li Mei Vermilya